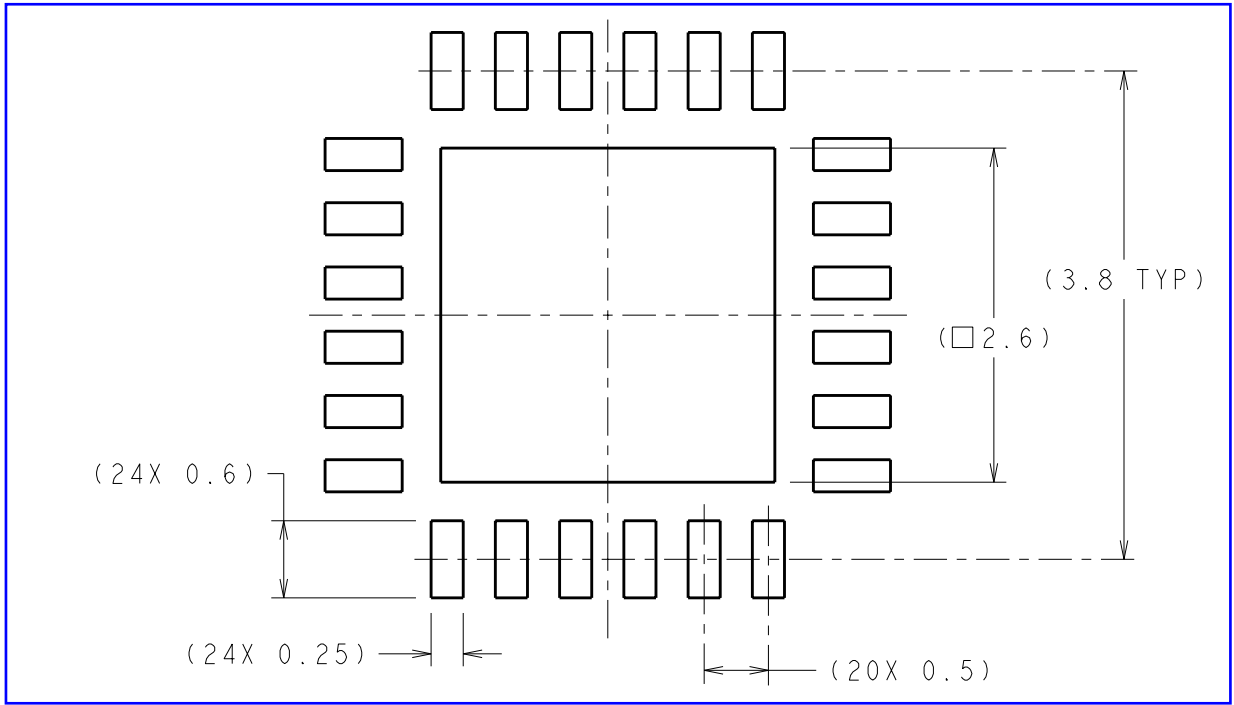
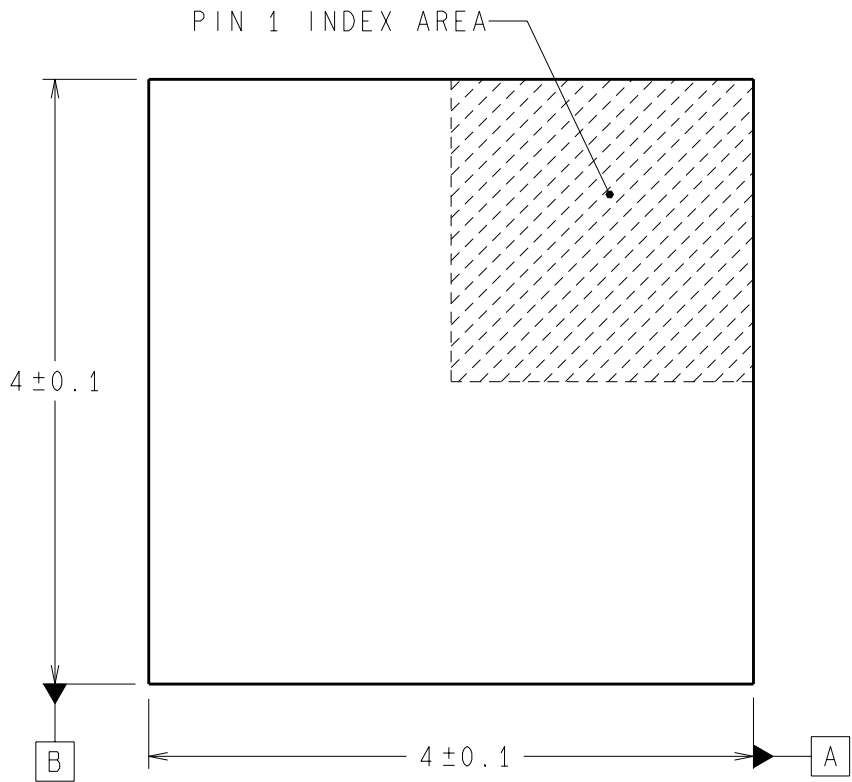


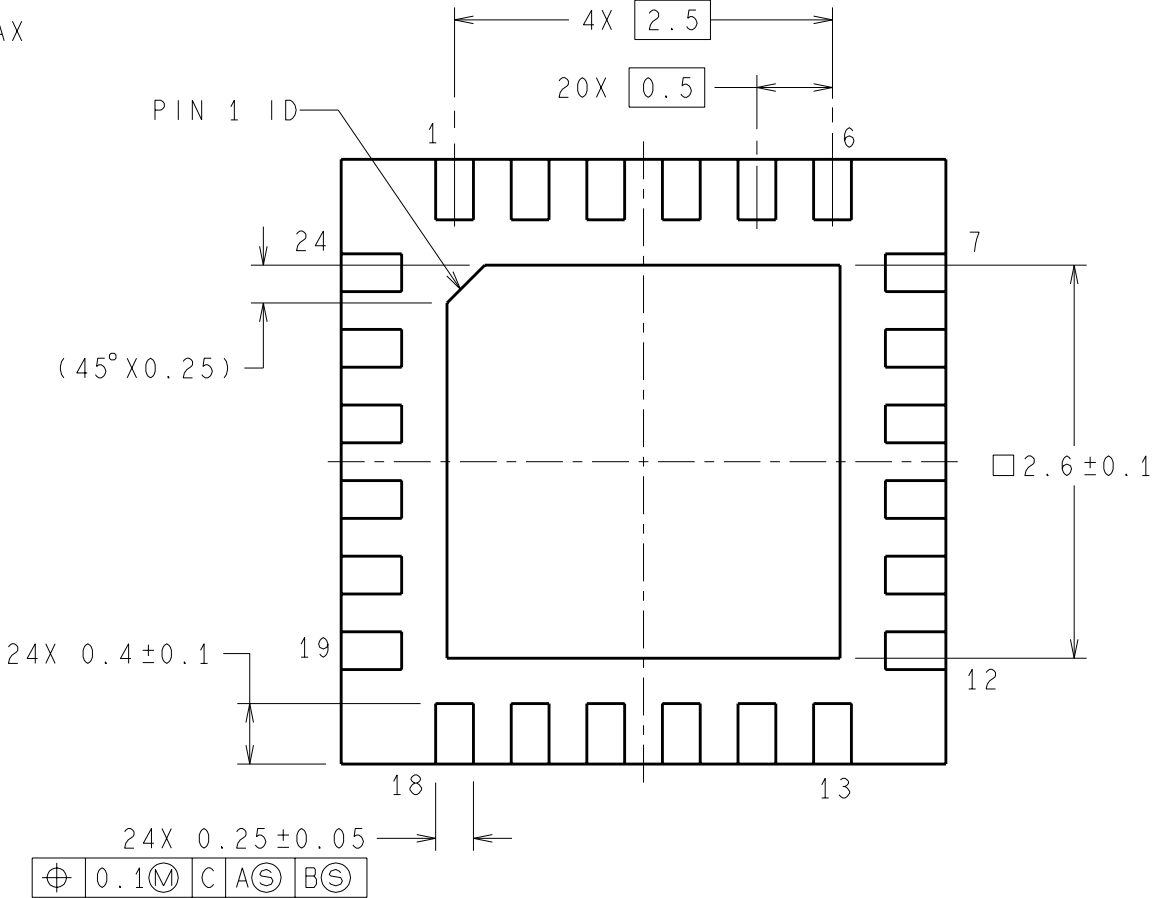
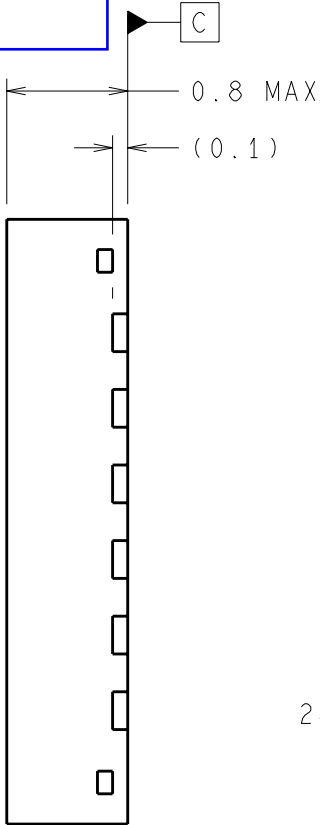
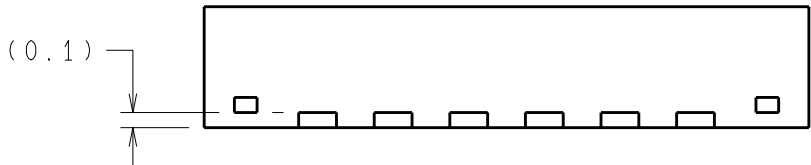
| REVISIONS |   |        |            |          |
|-----------|---|--------|------------|----------|
| REV       | DESCRIPTION   | E.C.N. | DATE       | BY/APP'D |
| A         | RELEASE TO DOCUMENT CONTROL   | 1007   | 04/25/2003 | TL/AT    |
| B         | REVISE TITLE; ADD BURR INFO NOTE; JEDEC INFO & TOP SIDE VIEW; CHANGE LAND PATT' DIM PER STD | 1050   | 08/01/2003 | TL/AT    |



RECOMMENDED LAND PATTERN





DIMENSIONS ARE IN MILLIMETERS  
DIMENSIONS IN ( ) FOR REFERENCE ONLY



NOTES: UNLESS OTHERWISE SPECIFIED.

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
2. MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
3. REFERENCE JEDEC REGISTRATION MO-220, WGGD-6.

| APPROVALS   |             | DATE              | <br>2900 Semiconductor Dr., Santa Clara, CA 95052-8090 |                |
|---|-------------|-------------------|---|----------------|
| DRAWN   | T. LEQUANG  | 04/17/2003        |   |                |
| DFTG. CHK.  | MARTA SUCHY | 08/01/2003        | LLP, PLASTIC, QUAD,<br>4x4x0.8mm BODY, 24 LD,<br>0.5mm PITCH, NO PULLBACK   |                |
| ENGR. CHK.  | ANNY TU     | 08/01/2003        |   |                |
| PROJECTION  |             | SCALE             | SIZE  | DRAWING NUMBER |
|  |             | NTS               | B   | (SC)MKT-SQA24A |
| MM  |             | FORMERLY: X-01939 |   | REV B          |
|   |             |                   |   | SHEET 1 of 1   |